

QFN Style Solder-Down Computer On Module

- 27mm square
- 2.6mm total height
- QS family pin-compatible
- Solder-down version
- QFN type lead style
 - 1mm pitch
 - 100 pads
 - Thermal pad
- Visual solder joint inspection possible after soldering
- Single-sided assembly
- 3.3V power supply



Key Features

- **Drop-in, pin-compatible upgrade for the QSMP-15**
- Standard configuration with:
 - STM32MP235C Dual ARM® Cortex®-A35, 1.2 GHz
 - RAM 512 MB DDR3L
 - ROM 4 GB eMMC
 - Grade Industrial
 - Temperature -25°C to 85°C
- Connectivity
 - RGB Display Interface
 - MIPI DSI
 - 2x USB 2.0
 - 1x Gb Ethernet, RGMII
 - 1x eMMC/SD
 - 2x CAN-FD
 - 3x UART, 2x I²C, 2x SPI, PWM, SAI
 - Up to 82x 3.3V General Purpose I/O

**2x
Cortex®-A35
STM32MP2**

OS Support

- Linux



STM32MP235

System

Power Supply Regulators
Crystal & Internal oscillators
Cyclic Redundancy Check (CRC)
Watchdogs (I & W)
96-bit unique ID
Up to 176 GPIOs

Security

RIF: Isolation and safe sharing of system resources
Octal SPI OTF Decryption
DRAM OTF Encryption/Dec.
DES, TDES, AES-256 with SCA
SHA-256/512, SHA-3, HMAC
PKA ECC/RSA with SCA
16x Tamper pins
T°, V, F and 32KHz detection
Secure RTC
Analog true RNG

Dual Cortex-A35 @ 1.2GHz

Core 1 @ 1.2GHz L1 32kB I / 32kB D	Core 2 @ 1.2GHz L1 32kB I / 32kB D
NEON SIMD MPE	NEON SIMD MPE
512kB L2 cache	
TrustZone	

Cortex-M33 @ 400MHz

16 kB I-Cache	16 kB D-Cache
FPU / MPU / NVIC	TrustZone

DDR3(L) 16b @ 1066MHz

Shared RAM 640kB including 128kB Retention RAM
Backup RAM 8kB / Boot ROM 128kB / OTP fuse 12kb

Control

3x 16-bit motor control PWM synchronized AC timer	
10x 16-bit timer	5x 16-bit LP timer
4x 32-bit timer	

Multimedia / AI

3D GPU: OpenGL ES / Vulkan / OpenCL	
AI / NN HW Acceleration: up to 0.6 TOPS	
1080p60 H.264, VP8 Video Decoder	
24b RGB Disp. 1080p @ 60fps	
DSI Display with PHY	
Lite-ISP (Camera Pipeline)	

Connectivity

1Gbps ETH/TSN port	1Gbps ETH/TSN port
3x CAN-FD / TTCAN	USB2.0 Host/Device HS
3x SDIO3.0 / SD 3 / eMMC 5.1	USB2.0 Host HS + HS PHY
16-bit SLC NAND, 8-bit-ECC	
2x Octal SPI, 8x SPI	
5x UART, 4x USART	4x I²C, 4x I3C, 3x I²S

Audio

SPDIF Rx 4 inputs
4x SAI
MDF 8 channels / 8 filters

Analog

3x 12-bit ADC 5 MSPS
Temperature sensor

QSMP-15 | QSMP-20 | QSMP-25 | Differentiating Features

	QSMP-15 STM32MP157	QSMP-20 STM32MP235	QSMP-25 STM32MP255
Primary Arm® Core	2x Cortex®-A7 650 MHz	2x Cortex®-A35 1.2 GHz	2x Cortex®-A35 1.5 GHz
Secondary Arm® Core	Cortex®-M4 250 MHz	Cortex®-M33 400 MHz	Cortex®-M33 400 MHz
RAM	512MB DDR3L	512MB DDR3L	1GB LPDDR4
ROM	4 GB eMMC	4 GB eMMC	4 GB eMMC
GPU	3D GPU	66 MTrg/s 400 MPix/s 12.8 GFlops	133 MTrg/s 800 MPix/s 25.6 GFlops
AI/ML/DSP	-	0.6 TOPS	1.2 TOPS
VPU	-	Decode	De-/Encode
Connectivity	USB 2.0	USB 2.0	USB 2.0, USB 3.0 or PCIe
Display Interface	RGB + MIPI-DSI	RGB + MIPI-DSI	LVDS
QS Size	100 pins 27mm square	100 pins 27mm square	108 pins 29mm square
Grade / Temperature	Industrial -25°C to 85°C	Industrial -25°C to 85°C	Industrial -40°C to 85°C

QSMP-20 Custom Options

	Standard	Options
RAM	512 MB DDR3L	256 MB / 1 GB
ROM	4 GB eMMC	8 GB
Temperature	-25°C to 85°C	-40°C to 85°C
MPU	MP235C	see below

MP2x1/x3/x5 Differentiating Features

	MP211 MP231 MP251	MP213 MP233 MP253	MP215 MP235 MP255
Cortex®-A35	1	1 2 2	1 2 2
GPU/NPU/VPU	-	- yes yes	- yes yes
Display Interface	- TTL TTL	- TTL TTL	TTL TTL/DSI TTL/DSI
FDCAN	-	2	2

MP21x/3x/5x Differentiating Features

	MP21x	MP23x	MP25x
Cortex®-A35	1.2/1.5 GHz	1.2/1.5 GHz	1.2/1.5 GHz
Cortex®-M33	300 MHz	400 MHz	400 MHz
Cortex®-M0+	-	-	200 MHz
L2 cache	128 kB	512 kB	512 kB
SRAM	64 kB	256 kB	256 kB
GPU/NPU	-	66 MTrg/s 400 MPix/s 12.8 GFlops	133 MTrg/s 800 MPix/s 25.6 GFlops
NPU	-	0.6 TOPS	1.2 TOPS
VPU	-	Decode	De-/Encode
Display Rotation	-	yes	yes
DDR3L Speed	800 MHz	933 MHz	933 MHz
SDRAM OTF en-/decryption	AES-256/192/128 SCA protection	AES-128	AES-128
SHA-512, SHA-3 HMAC (HASH1/2)	2	1	1
RNG (RNG1/2)	2	1	1
Tamper trigger via monitoring of voltages	yes	-	-
Secure isolation level	4	2	2
Encryption of the first stage boot loader	AES-256	AES-128	AES-128
Secure Boot Signature	ECDSA P-384 BrainpoolP384	P-256 P256	P-256 P256
Additional 384 authentication key	yes	-	-
Increased ROM code execution performance	yes	-	-

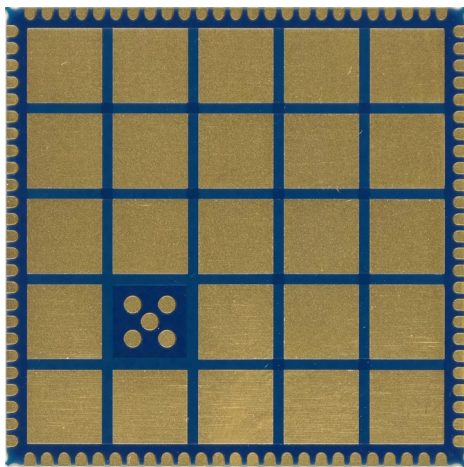
QFN Style Computer On Module Advantages

Defined Return Path

The reason PCB layout becomes more and more important is because of the trend to faster, higher integrated, smaller formfactors, and lower power electronic circuits. The higher the switching frequencies are, the more radiation may occur on a PCB. With good layout, many EMI problems can be minimized to meet the required specifications.

When a module or component is used in a design, the supplier specifies the basis for such a layout. It's not only the pinout which should lead to an easy wiring without the need for crossings. He also has to provide a proper solution for the signal path back to the module. If this return path, mostly the ground plane, cannot be connected near the signal pin, the return current has to take another way and this may result in a loop area. The larger the area, the more radiation and EMI problems may occur.

Ka-Ro QSCOM modules uses a large ground pad on the bottom side. With this a defined ground plane connection is available for all signals. In addition to have a good return path for all signals this large ground pad can be used for cooling.



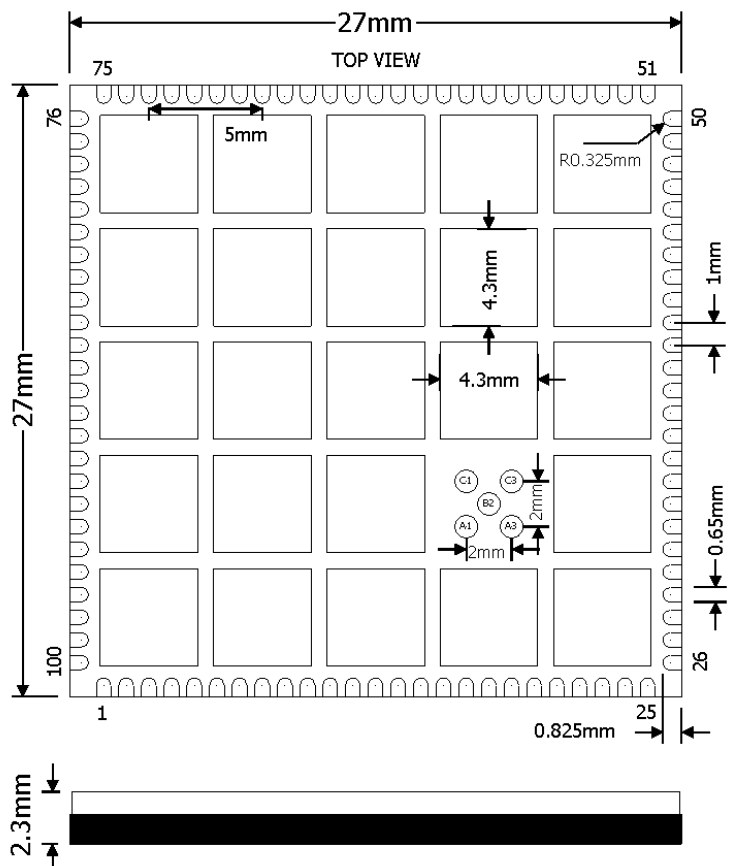
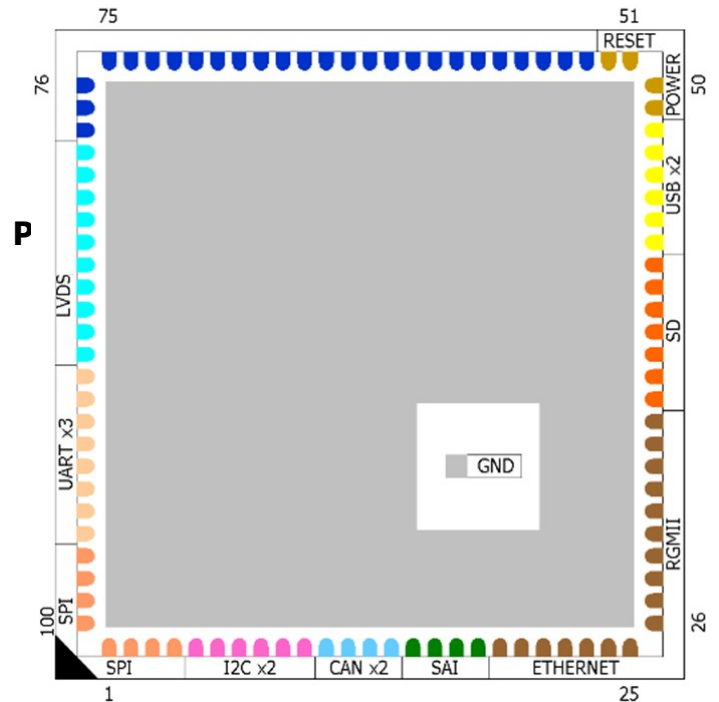
Easy Wiring - Even 2-layer printed circuit boards can be used.

With a solid ground plane on the bottom layer, high speed signals can be routed on the top layer at a defined impedance. However, this is only possible if a peripheral or plug can be connected directly without crossing other routes.

Advanced Soldering

Using a large solder pad underneath the component has not only electrical and thermal advantages. It is also used to hold the component at a defined height during soldering, without the solder being compressed by the weight of the components, which could result in short circuits.

Standard Contact Assignments

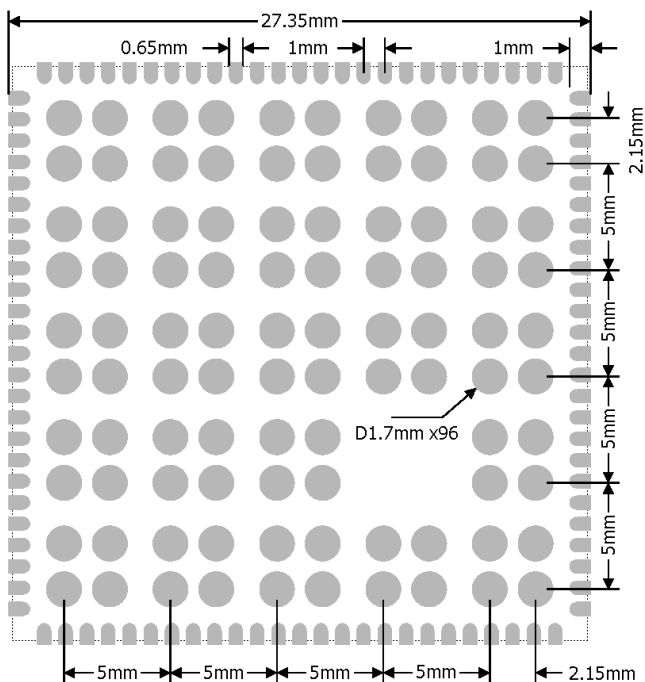


Soldering Recommendations

Ka-Ro QSCOM modules are compatible with industrial standard reflow profile for Pb-free solders. Ka-Ro will give following recommendations for soldering the module to ensure reliable solder joint and operation of the module after soldering. Since the profile used is process and layout dependent, the optimum profile should be studied case by case. Thus following recommendations should be taken as a starting point guide.

- Refer to technical documentations of particular solder paste for reflow profile configurations
- Avoid using more than one flow.
- A 150µm stencil thickness is recommended.
- Aperture size of the stencil should be 1:1 with the pad size.
- A low residue, "no clean" solder paste should be used due to low mounted height of the component.

Recommended stencil design

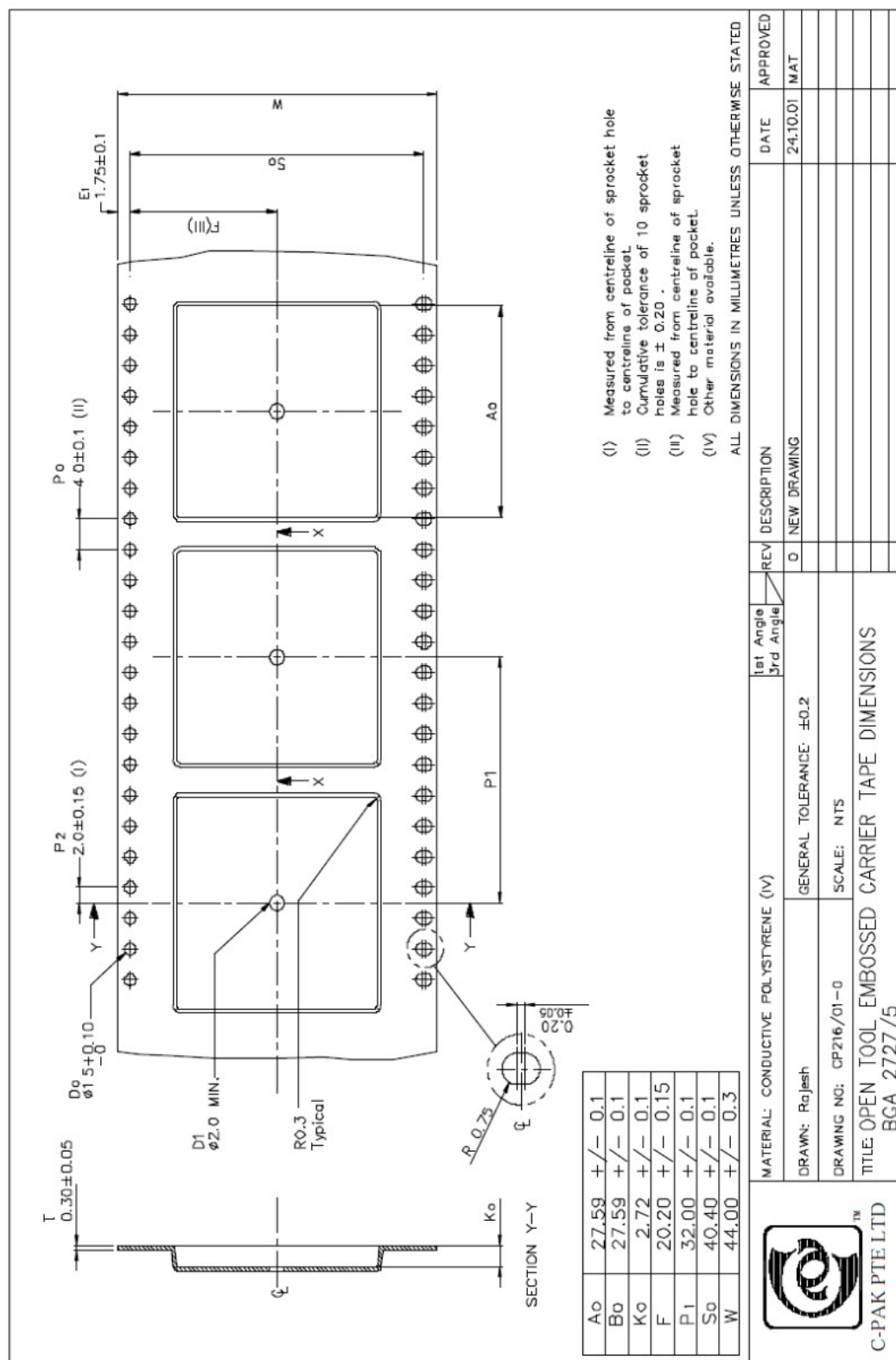


Aperture size of the stencil is 1:1 with the pad size. Four 1.7mm diameter bumps are used for each of the 4.3mm square GND pads sections giving a 50% solder paste padding. The lower component settling with this ensures that the pads at the edge are always soldered even at vertical misalignment by distortion or warping.

Thermal Considerations

A low residue, "no clean" solder paste should be used due to low mounted height of the component. The QSCOM module consume more than 1 W of DC power. In any application where high ambient temperatures for more than a few seconds can occur, it is important that a sufficient cooling surface is provided to dissipate the heat. The thermal pad at the bottom of the module must be connected to the application board ground planes by soldering. The application board should provide a number of vias under and around the pad to conduct the produced heat to the board ground planes, and preferably to a copper surface on the other side of the board in order to conduct and spread the heat. The module internal thermal resistance should in most cases be negligible compared to the thermal resistance from the module into air, and common equations for surface area required for cooling can be used to estimate the temperature rise of the module. Only copper planes on the circuit board surfaces with a solid thermal connection to the module ground pad will dissipate heat. For an application with high load the maximum allowed ambient temperature should be reduced due to inherent heating of the module, especially with small fully plastic enclosed applications where heat transfer to ambient air is low due to low thermal conductivity of plastic. The module measured on the evaluation board exhibits a temperature rise of about 20°C above ambient temperature. An insufficiently cooled module will rapidly heat beyond operating range in ambient room temperature.

Packaging



PINOUT (STM32MP2 pads named PA, PB, etc. can be used as GPIO ports)

PIN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
1st SPI							
1	SPIA_NSS	PD5	TRACED1 SPI4_NSS HDP_HDP4 SAI1_D4	SAI1_FS_B - - -	TIM1_CH3N TIM4_CH2 OCTOSPIM_P1_IO1 - -	- DCMIPP_D13 - -	
2	SPIA_MISO	PD4	TRACED0 SPI4_MISO HDP_HDP3 SAI1_D3	SAI1_SD_B - - -	TIM1_CH4N TIM4_CH1 OCTOSPIM_P1_IO0 - -	- DCMIPP_D14 - -	
3	SPIA_MOSI	PD6	TRACED2 SPI4_MOSI HDP_HDP5 -	SAI1_SCK_B MDF1_SDI2 - -	TIM1_CH2N TIM4_CH3 OCTOSPIM_P1_IO2 - -	- DCMIPP_D12 - -	
4	SPIA_SCK	PD7	DEBUG_TRACED3 SPI4_SCK SPI1_RDY -	SAI1_MCLK_B MDF1_CK12 - -	TIM1_CH1N TIM4_CH4 OCTOSPIM_P1_IO3 - -	- DCMIPP_D11 - -	
I2C							
5	I2CA_SCL	PF2	- SPI3_RDY -	- - -	TIM12_CH1 I2C2_SCL ETH1_MDIO ETH2_MII_COL	FMC_NE4 I3C2_SCL - -	
6	I2CA_SDA	PB4	- SPI2_RDY UART4_CTS	SAI4_FS_B - TIM14_CH1	- I2C2_SDA OCTOSPIM_P2_IO4	- I3C2_SDA -	Connected to both ports due to compatibility of the MP2xx series
		PD15	- SPI1_RDY -	- DSIHOST_TE I2C5_SDA FDCAN1_TX	TIM1_BKIN2 TIM5_ETR I2C7_SCL FMC_D3/FMC_DA3	SDMMC3_CKIN DCMIPP_D0/DCMI_D0/PSSI_D0 EVENTOUT	
7	INTA	PH3	- I2S1_WS/SPI1_NSS	- UART7_RX TIM17_CH1N	- TIM5_CH3 I2C7_SCL	- -	Connected to both ports due to compatibility of the MP2xx series
		PH8	- I2S1_SDI/SPI1_MISO SPDIFRX_IN3	- UART4_RX UART7_CTS	- TIM5_CH1 I2C3_SMBA I2C2_SMBA	- -	
8	I2CB_SCL	PZ1	- LPTIM3_CH1 SPI8_MISO	TIM8_CH2 LPUART1_RX LPTIM5_ETR	I2C8_SCL I2C8_SMBA -	- -	
9	I2CB_SDA	PZ0	- LPTIM3_IN1 SPI8_MOSI	TIM8_CH1 LPUART1_TX LPTIM5_OUT	I2C8_SDA LPTIM3_CH2 I3C4_SDA	- -	
10	INTB	PD14	- I2S1_MCK	- FDCAN1_RX	TIM11_CH1 - I2C7_SDA FMC_D4/FMC_DA4	SDMMC3_D3 DCMIPP_D1 -	
CAN							
11	CANA_RX	PB11	- I2S3_MCK -	- USART1_CTS/USART1_NSS FDCAN1_RX	- TIM12_CH2 OCTOSPIM_P2_NCLK OCTOSPIM_P2_NCS2	FMC_D14/FMC_DA14 OCTOSPIM_P1_NCS2 -	
12	CANA_TX	PB9	- SPI3_RDY -	- USART1_DE/USART1_RTS FDCAN1_TX	- TIM10_CH1 OCTOSPIM_P2_DQS OCTOSPIM_P2_NCS2	FMC_D13/FMC_DA13 -	
13	CANB_RX	PA5	- SPI4_MOSI	SAI2_MCLK_B SAI2_SD_B USART2_DE/USART2_RTS FDCAN2_RX	TIM2_CH4 - LTDC_G0	FMC_A0 DCMI_D13/PSSI_D13 -	
14	CANB_TX	PC3	LPTIM1_IN2 I2S3_WS/SPI3_NSS -	- USART6_DE/USART6_RTS FDCAN2_TX	- ETH2_RX_CTL/CRS_DV ETH1_MII_RX_ER	LTDC_G6 DCMI_D3/PSSI_D3 -	
SAI							
15	SAI_TX	PD1	- HDP_HDP1 I2S1_SDI/SPI1_MISO SAI1_CK2	- SAI4_SD_A UART7_DE/UART7_RTS TIM15_CH1	TIM1_BKIN - OCTOSPIM_P1_NCLK OCTOSPIM_P1_NCS2	OCTOSPIM_P2_NCS2 DCMIPP_HSYNC -	

PIN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
16	SAI_RX	PB5	- I2S2_MCK UART4_DE/UART4_RTS	SAI4_SD_B - -	- I2C2_SCL OCTOSPIM_P2_IO5	FMC_D8/FMC_DA8 I3C2_SCL SDMMC3_D123DIR	
17	SAI_SCK	PD2	- HDP_HDP2 I2S1_WS/SPI1_NSS SAI1_CK1	SAI4_SCK_A UART7_CTS TIM15_BKIN	TIM1_ETR - OCTOSPIM_P1_DQS OCTOSPIM_P1_NCS2	DCMIPP_VSYNC -	
18	SAI_FS	PD0	DEBUG_TRACECLK HDP_HDP0 - SAI1_D2	SAI4_FS_A UART7_RX TIM15_CH2	- OCTOSPIM_P1_CLK -	DCMIPP_PIXCLK -	
ETHERNET 1							
19	ENET_RST	PB2	- I2S2_SDO/SPI2_MOSI	- MDF1_CK13 TIM17_BKIN TIM16_BKIN	- OCTOSPIM_P2_IO2	-	
20	ENET_CK125	PH9	-	SAI3_MCLK_A - USART6_RX TIM15_CH1N	ETH1_RGMII_CLK125 ETH1_MII_RX_ER	-	ADC3_INP4
21	ENET_INT	PC6	- RTC_REFIN SPDIFRX_IN0	MDF1_CK11 -	TIM8_CH1 - ETH2_MDC ETH1_MII_CRS	FMC_A24 ETH1_PHY_INTN LTDC_CLK	ADC1_INP9, ADC1_INN5, ADC2_INP9, ADC2_INN5
22	ENET_MDIO	PA10	- SPI4_MISO	SAI2_SD_B - USART2_RX LPTIM5_IN1	TIM2_CH2 - ETH1_MDIO	LTDC_R6 DCMIPP_D15/PSSI_D15	
23	ENET_MDC	PF4	- RTC_OUT2	SAI3_SCK_A - USART6_RX TIM4_CH4	ETH1_MDC ETH2_CLK ETH2_PPS_OUT ETH1_PPS_OUT	LTDC_B7	
24	ENET_RXC	PA14	- SPI8_NSS LPTIM2_CH2	SAI4_FS_B MDF1_CCK1	- ETH1_RXC/REF_CLK	-	
25	ENET_RX_CTL	PA11	- SPI8_SCK LPTIM2_CH1	SAI4_SD_B -	- ETH1_RX_CTL/CRS_DV	-	
26	ENET_RXD0	PF1	- SPI8_MISO LPTIM2_IN2	SAI4_SCK_B - USART2_CK	- ETH1_RXD0	-	
27	ENET_RXD1	PC2	- SPI8_MOSI LPTIM2_IN1	SAI4_MCLK_B MDF1_SDI3 USART2_DE/USART2_RTS	- ETH1_RXD1	-	
28	ENET_RXD2	PH12	- I2S3_WS/SPI3_NSS	-	TIM10_CH1 - ETH1_RXD2	-	
29	ENET_RXD3	PH13	- I2S3_CK/SPI3_SCK	- TIM15_BKIN	TIM11_CH1 - ETH1_RXD3	-	
30	ENET_TX_CTL	PA13	- SPI8_RDY I2S3_MCK LPTIM2_ETR	MDF1_CK13 USART2_CTS/USART2_NSS	I2C7_SMBA ETH1_TX_CTL/TX_EN	-	
31	ENET_TXC	PC0	LPTIM1_CH1 -	SAI3_MCLK_B USART6_TX -	DCMIPP_D0 ETH2_RMII_REF_CLK ETH1_MII_TX_CLK	ETH1_RGMII_GTX_CLK LTDC_G7	
32	ENET_TXD3	PH11	-	SAI3_FS_A - TIM15_CH2	ETH2_MDIO ETH1_TXD3	-	
33	ENET_TXD2	PH10	- I2S1_CK/SPI1_SCK	SAI3_SCK_A - TIM15_CH1	ETH2_MDC ETH1_TXD2	-	ADC3_INP8, ADC3_INN4
34	ENET_TXD1	PC1	- I2S3_SDO/SPI3_MOSI	- USART2_TX	I2C7_SCL ETH1_TXD1	-	

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35	ENET_TXD0	PA15	I2S3_SDI/SPI3_MISO	USART2_RX	I2C7_SDA ETH1_TXD0	- - -	
SD							
36	SD_CD	PB3	- I2S2_WS/SPI2_NSS	- MDF1_SDI3	- OCTOSPIM_P2_IO3	FMC_NCE3 - -	
37	SD_D1	PE5	DEBUG_TRACED1 LPTIM2_IN2 I2S1_WS/SPI1_NSS I2S3_WS/SPI3_NSS	SAI1_FS_B USART3_DE/USART3_RTS FDCAN1_RX	- SDMMC1_D1	- - -	
38	SD_D0	PE4	DEBUG_TRACED0 LPTIM2_IN1 I2S1_SDO/SPI1_MOSI I2S3_SDI/SPI3_MISO	SAI1_SD_B USART3_CTS/USART3_NSS FDCAN1_TX	- SDMMC1_D0	- - -	
39	SD_CLK	PE3	DEBUG_TRACECLK SPI1_RDY I2S3_CK/SPI3_SCK	SAI1_MCLK_B USART3_TX	TIM11_CH1 SDMMC1_CK	- - -	
40	SD_CMD	PE2	- LPTIM2_ETR I2S1_SDI/SPI1_MISO I2S3_SDO/SPI3_MOSI	SAI1_SCK_B	TIM10_CH1 SDMMC1_CMD	- - -	
41	SD_D3	PE1	DEBUG_TRACED3 LPTIM2_CH2 I2S1_MCK I2S3_MCK	- USART3_RX	- SDMMC1_D3	- - -	
42	SD_D2	PE0	DEBUG_TRACED2 LPTIM2_CH1 I2S1_CK/SPI1_SCK SPI3_RDY	- USART3_CK	- SDMMC1_D2	- - -	
USB							
43	USBA_VBUS	Not connected					
44	USBA_DN	USBH_HS_DM					
45	USBA_DP	USBH_HS_DP					
46	USBB_VBUS	PC5	- SPDIFRX_IN1	- MDF1_SDI1	TIM8_CH1N I2C4_SDA ETH2_MDIO ETH1_MII_COL	FMC_A25 ETH1_PPS_OUT LTDC_DE EVENTOUT	10K/20K voltage divider ADC1_INP10, ADC2_INP10, ADC3_INP10, TAMP_IN6
47	USBB_DN	USB3DR_DM					
48	USBB_DP	USB3DR_DP					
POWER SUPPLY & RESET							
49	VIN	3.3V power supply input					
50							
51	NRST	Open drain reset to reset of external devices, or to reset the device. Connected to STM32MP2 NRST and PCA9450 POR_B, 10K-PU					
52	BOOT_MODE	Connected to STM32MP2 BOOT1, 10K-PU. BOOT[0,2,3]=L					H: Boot from eMMC L: Boot from USB
DISPLAY							
53	LCD_DE	PI5	- SPI5_MOSI I2S1_SDO/SPI1_MOSI	- UART5_CTS	TIM5_CH2 -	- LTDC_DE DCMI_D1/PSSI_D1	
54	LCD_VSYNC	PI6	- RCC_MCO_1	- USART3_TX TIM2_ETR	TIM3_CH1 -	- LTDC_VSYNC	WKUP4
55	LCD_HSYNC	PG2	RTC_REFIN I2S3_MCK	SAI2_FS_A USART3_CK	TIM5_CH3 ETH2_MII_TX_CLK ETH2_RGMII_CLK125	FMC_CLK LTDC_HSYNC	WKUP5, ADC1_INP2, ADC2_INP2
56	LCD_CLK	PF12	DEBUG_TRACECLK SPI5_MISO I2S1_SDI/SPI1_MISO	-	TIM5_CH1 -	- LTDC_CLK DCMI_D0/PSSI_D0	
57	LCD_R1	PA4	-	- USART2_TX FDCAN2_TX	TIM2_CH1 LTDC_R1	ETH1_PTP_AUX_TS -	

PIN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
58	LCD_R2	PC11	- LPTIM1_CH1 SPI5_NSS	SAI2_MCLK_A UART5_DE/UART5_RTS USART3_DE/USART3_RTS TIM3_CH1	TIM5_ETR - ETH2_RXD3 -	FMC_NBL1 LTDC_R2 DCMIPP_D10 -	ADC1_INP7, ADC1_INN3, ADC2_INP7, ADC2_INN3, ADC3_INP7, ADC3_INN3
59	LCD_R3	PA1	- - -	SAI3_SD_A USART1_DE/USART1_RTS USART6_CK TIM4_CH2	- - - LTDC_R3	- DCMI_D5/PSSI_D5 -	
60	LCD_R4	PF15	DEBUG_TRACED2 HDP_HDP2 SPI2_RDY USART6_CTS/USART6_NSS	I2S2_CK/SPI2_SCK - USART3_CK TIM2_CH2	TIM3_ETR - - -	LTDC_R4 - -	
61	LCD_R5	PG5	DEBUG_TRACED3 HDP_HDP3 -	- - -	- - -	LTDC_R5 DCMIPP_PIXCLK -	
62	LCD_R6	PF3	- - -	SAI2_SCK_B MDF1_CCK0 -	TIM8_BKIN2 ETH1_CLK ETH2_PPS_OUT	FMC_A20 LTDC_R6 DCMI_HSYNC/PSSI_DE	ADC1_INP16, ADC1_INN15
63	LCD_R7	PG7	DEBUG_TRACED5 HDP_HDP5 SPI5_NSS I2S1_WS/SPI1_NSS	- - -	TIM5_ETR - -	LTDC_R7 DCMI_VSYNC/PSSI_RDY	
64	LCD_G2	PC9	- RCC_MCO_1 I2S3_SDI/SPI3_MISO -	SAI2_SCK_A - - TIM13_CH1	TIM8_CH4N USBH_HS_OVRCUR ETH2_TXD2 USB3DR_OVRCUR	FMC_A22 LTDC_G2 DCMIPP_D7 -	ADC1_INP8, ADC1_INN4, ADC2_INP8, ADC2_INN4
65	LCD_G3	PG9	DEBUG_TRACED7 - -	- UART5_TX -	TIM5_CH4 - -	LTDC_G3 DCMIPP_D3/DCMI_D3/PSS I_D3 -	
66	LCD_G4	PA6	- - -	SAI2_FS_B - USART2_CK TIM13_CH1	TIM2_ETR - LTDC_G4	FMC_NE1 DCMI_D12/PSSI_D12 -	
67	LCD_G5	PG11	DEBUG_TRACED9 HDP_HDP1 -	- - FDCAN1_TX	TIM8_CH4 - -	LTDC_G5 DCMIPP_D5 -	
68	LCD_G6	PG12	DEBUG_TRACED10 HDP_HDP2 -	- - FDCAN1_RX	TIM8_CH1N - -	LTDC_G6 DCMI_D6/PSSI_D6 -	
69	LCD_G7	PA9	- - -	SAI2_SCK_B - USART2_CTS/USART2_NSS LPTIM5_ETR	TIM2_CH3 - ETH1_MDC -	LTDC_G7 DCMIPP_D14/PSSI_D14 -	
70	LCD_B1	PG14	DEBUG_TRACED12 HDP_HDP4 -	- - USART1_TX	TIM8_BKIN2 - -	LTDC_B1 DCMI_D9/PSSI_D9 -	
71	LCD_B2	PG15	DEBUG_TRACED13 HDP_HDP5 -	- - USART1_RX	TIM8_ETR - -	LTDC_B2 DCMI_D10/PSSI_D10 -	
72	LCD_B3	PI0	DEBUG_TRACED14 HDP_HDP6 -	SAI4_MCLK_B - USART1_CK -	TIM8_BKIN - -	LTDC_B3 DCMI_D11/PSSI_D11 -	
73	LCD_B4	PC7	- - -	SAI3_SD_B - -	TIM8_CH2N - ETH2_TXD0 ETH1_MII_TXD2	LTDC_B4 DCMIPP_D1 -	ADC3_INP9, ADC3_INN5
74	LCD_B5	PA7	- - AUDIOCLK	MDF1_CCK0 USART1_CTS/USART1_NSS TIM4_ETR	I2C2_SMBA LTDC_B5 -	DCMI_D6/PSSI_D6 -	
75	LCD_B6	PF5	- - -	SAI3_MCLK_A - USART6_TX TIM4_CH3	ETH1_MDIO ETH1_CLK ETH2_PHY_INTN ETH1_PHY_INTN	LTDC_B6 - -	
76	LCD_B7	PI4	- - LPTIM1_CH1	SAI4_FS_B - -	TIM8_CH3 - -	LTDC_B7 DCMIPP_D15/PSSI_D15 -	

Display Control

PIN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
77	LCD_EN	PC4	- - -	SAI3_FS_B - -	- - ETH2_TX_CTL/TX_EN	ETH1_RGMII_CLK125 LTDC_R0 -	TAMP_IN1
78	LCD_BL	PF13	DEBUG_TRACED0 HDP_HDP0 AUDIOCLK USART6_TX	I2S2_WS/SPI2_NSS USART3_CTS/USART3_NSS -	TIM3_CH3 - -	- LTDC_R2 -	

MISC

79	LCD_R0 CSI_CKP LVDS1_CLKP	PH4	- - -	- UART7_TX TIM17_BKIN	- TIM5_CH2 LTDC_R0 USB3DR_OVRCUR	USBH_HS_OVRCUR ETH1_PTP_AUX_TS -	BOOTFAILN
80	LCD_G0 DSI_DP3 LVDS0_TX3P	PF8	- RTC_REFIN - SAI3_SCK_B	- USART3_RX TIM12_CH2	- ETH1_CLK ETH2_RGMII_CLK125 ETH2_MII_RX_ER	ETH2_RX_DV/CRS_DV LTDC_G0 -	
81	LCD_G1 DSI_DN3 LVDS0_TX3N	PC12	- LPTIM1_CH2 - -	- MDF1_CK12 -	TIM8_CH3 - ETH2_RXD1 ETH1_MII_RXD3	- LTDC_G1 DCMIPP_D5/DCMI_D5/PSSI_I_D5	ADC1_INP17
82	LCD_B0	PA2	- LPTIM2_IN1 -	- USART1_RX -	I3C1_SDA - I2C1_SDA LTDC_B0	- DCMI_D3/PSSI_D3 -	

MIPI-DSI

83	DSI_DP1	DSIHOST_D1P					
84	DSI_DN1	DSIHOST_D1N					
85	DSI_DP0	DSIHOST_D0P					
86	DSI_DN0	DSIHOST_D0N					
87	DSI_CKP	DSIHOST_CKP					
88	DSI_CKN	DSIHOST_CKN					

UART

89	UARTA_RXD	PB6	- I2S2_SDI/SPI2_MISO UART4_RX	SAI4_SCK_B - -	- - OCTOSPIM_P2_IO6	FMC_D9/FMC_DA9 SDMMC3_D0DIR -	
90	UARTA_TXD	PH7	- I2S1_SDO/SPI1_MOSI	UART4_TX UART7_DE/UART7_RTS TIM17_CH1	TIM5_CH4 I2C7_SDA -	- - -	
91	UARTB_RXD	PH5	- - -	SAI2_FS_A - TIM2_CH1	UART7_RX - LTDC_G1 USB3DR_VBUSEN TIM1_BKIN2	USBH_HS_VBUSEN ETH2_PTP_AUX_TS -	WKUP2
92	UARTB_TXD	PD3	SAI1_MCLK_A I2S2_CK/SPI2_SCK SAI1_D1	SAI4_MCLK_A UART7_TX TIM15_CH1N	OCTOSPIM_P1_NCS1 -	DCMIPP_D15/PSSI_D15 -	
93	UARTC_RXD	PG10	DEBUG_TRACED8 HDP_HDP0 -	UART5_RX -	TIM8_CH4N -	LTDC_G4 DCMIPP_D4/PSSI_D4	
94	UARTC_TXD	PA0	LPTIM1_CH2 SPI5_RDY -	SAI2_MCLK_B UART5_TX USART3_TX TIM3_ETR	TIM5_CH2 ETH2_MII_RXD2	FMC_NL DCMI_D9/PSSI_D9	WKUP1
95	UARTC_CTS	PG1	LPTIM1_IN1 I2S3_MCK -	SAI2_SD_A UART5_CTS USART3_CTS/USART3_NSS	TIM5_CH4 - ETH2_MII_RX_ER ETH2_MII_RXD3	FMC_NBL0 LTDC_VSYNC DCMIPP_D11/PSSI_D11	CTS/RTS input signal WKUP3, ADC1_INP6, ADC1_INN2, ADC2_INP6, ADC2_INN2, TAMP_IN4
96	UARTC_RTS	PG8	DEBUG_TRACED6 HDP_HDP6 SPI5_RDY SPI1_RDY	USART6_CK UART5_DE/UART5_RTS -	TIM5_CH3 -	LTDC_G2 DCMIPP_D2/PSSI_D2	RTS/CTS output signal

2nd SPI

97	SPIB_NSS	PB1	- I2S3_WS/ SPI3_NSS -	- - TIM16_CH1N	- - OCTOSPIM_P2_IO1	FMC_NCE4 -	
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PIN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
98	SPIB_MISO	PB10	I2S3_SDI/ SPI3_MISO - -	- - USART1_RX TIM17_CH1N	- - OCTOSPIM_P2_CLK -	FMC_D15/FMC_DA15 - - -	
99	SPIB_MOSI	PB8	I2S3_SDO/ SPI3_MOSI - -	PCIE_CLKREQN - USART1_TX TIM17_CH1	TIM20_CH4 - OCTOSPIM_P2_NCS1 -	FMC_D12/FMC_DA12 - - EVENTOUT	
100	SPIB_SCK	PF0	- I2S3_CK/ SPI3_SCK -	- - - FDCAN2_RX	TIM12_CH2 I2C2_SDA ETH1_MDC ETH2_MII_CRS	- I3C2_SDA - -	ADC1_INP11, ADC2_INP11, ADC3_INP11

Pins used for manufacturing and debugging – leave unconnected

PIN	(SPM32MP2 PAD NAME)	PIN	(SPM32MP2 PAD NAME)	PIN	(SPM32MP2 PAD NAME)
C1	JTAG_TDI (JTDI)			C3	JTAG_TCK (JTCK_SWCLK)
		B2	JTAG_TDO (JTDO_TRACESWO)		
A1	JTAG_TRST_B (NJTRST)			A3	JTAG_TMS (JTMS_SWDIO)

Onboard peripherals wiring

USED FOR		MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-14	Remarks
eMMC	CMD	PE15	- - - -	SAI1_SCK_A - - TIM15_CH1N	TIM1_CH1N - - FMC_NOE	SDMMC2_CMD - - -	10K-PU
	CLK	PE14	- - -	SAI1_MCLK_A - - TIM15_BKIN	TIM1_BKIN - - FMC_NWE	SDMMC2_CLK - - -	10K-PU
	DAT0	PE13	- - -	SAI1_SD_A - - TIM15_CH1	TIM1_CH2N - - FMC_RNB	SDMMC2_D0 - - -	10K-PU
	DAT1	PE11	- - -	SAI1_FS_A - - TIM15_CH2	TIM1_CH3N - - FMC_A16/FMC_CLE	SDMMC2_D1 - - -	
	DAT2	PE8	SAI4_D3 SPI4_MOSI SAI4_CK1	SAI4_MCLK_A MDF1_CKIO - -	TIM1_CH1 - - FMC_A17/FMC_ALE	SDMMC2_D2 - - -	
	DAT3	PE12	- SPI4_NSS SAI4_CK2	SAI4_SCK_A MDF1_SDI0 USART1_RTS	TIM1_CH2 - FMC_NE2 FMC_NCE1	SDMMC2_D3 - - -	
	DAT4	PE10	- SPI4_SCK SAI4_D1	SAI4_SD_A USART1_CTS -	TIM1_CH3 - FMC_NE3 FMC_NCE2	SDMMC2_D4 SDMMC2_CKIN -	
	DAT5	PE9	- SPI4_MISO SAI4_D2	SAI4_FS_A USART1_CK -	TIM1_CH4 - - FMC_D0/FMC_DA0	SDMMC2_D5 SDMMC2_CDIR -	
	DAT6	PE6	- SPI4_RDY -	SPDIFRX_IN2 USART1_TX -	TIM1_ETR - - FMC_D1/FMC_DA1	SDMMC2_D6 SDMMC2_D0DIR -	
	DAT7	PE7	- - SAI4_D4	SPDIFRX_IN3 USART1_RX -	TIM1_CH4N - TIM14_CH1 FMC_D2/FMC_DA2	SDMMC2_D7 SDMMC2_D123DIR -	
PMIC PCA9450A	SDA	PI1	DEBUG_TRACED15 HDP_HDP7 -	- - -	TIM8_CH3N I2C1_SDA I3C1_SDA -	- LTDC_B4 DCMIPP_D8/PSSI_D8	1K-PU
	SCL	PG13	DEBUG_TRACED11 HDP_HDP3 SPI7_SCK -	- MDF1_CKIO -	TIM8_CH2N I2C1_SCL I3C1_SCL -	- LTDC_G7 DCMIPP_D7/PSSI_D7	10K-PU
	IRQ_B	PD11	DEBUG_TRACED7 - I2S1_CK/SPI1_SCK SAI1_MCLK_A	UART4_TX MDF1_CKIO -	TIM1_CH1 - OCTOSPIM_P1_IO7 SDMMC1_D4	SDMMC1_CKIN DCMIPP_D7/DCMIP_D7/PSSI_D7 -	10K-PU
	POR_B	NRST					10K-PU
	PMIC_ON_REQ	PWR_ON					
	PMIC_STBY_REQ	PWR_LP					
	WDOG_B	PD8	DEBUG_TRACED4 SPI4_RDY I2S1_MCK SAI1_FS_A	UART4_CTS MDF1_SDI1 -	TIM1_CH4 TIM4_ETR OCTOSPIM_P1_IO4 SDMMC1_D7	SDMMC1_D123DIR DCMIPP_D10/PSSI_D10 -	10K-PU

Electrical characteristics**Absolute maximum ratings**

Parameter	Symbol	Min	Max	Remarks
Power supply	VIN	0V	3.9V	
Input voltage on USB VBUS pins	USBA_VBUS USBB_VBUS	0V	6V	
Input voltage on USB DN/DP pins	USBA_DN/DP USBB_DN/DP	0V	5.5V	
Input voltage on any other pins		0V	3.9V	
Storage temperature range	T _{STORAGE}	-40°C	85°C	

Operating ranges

Parameter	Symbol	Min	Max	Remarks
Power supply	VIN	3.1V	3.6V	
I/O input low level voltage	V _{IL}	-	0.3 x VIN	
I/O input high level voltage	V _{IH}	0.7 x VIN	-	
I/O output voltage	Refer to STM32MP2 datasheet, chap. Output voltage levels.			VDD=VIN=3.3V typ.
Operating temperature range	T _{AMB}	-25°C	85°C	
Processor junction temperature	T _J	-40°C	125°C	

Power supply currents

Parameter	Symbol	VIN	Current	Remarks
At U-Boot prompt	I _{UBOOT}	3.3V	195mA	All pins left unconnected
At Linux prompt	I _{LINUX}	3.3V	170mA	
Sleep	I _{SLEEP}	3.3V	6mA	
Maximum calculated	I _{MAX}	3.3V	700mA	Calculated on max. IDD's @ 80% onboard power supply efficiency.
Power supply rating	I _{SUPP}	3.3V	1A	With margin for sizing the power supply